BOTTOM VIEW

TOP VIEW

FF1156 – Sn/Pb SOLDER BALLS
FFG1156 – Sn/Ag/Cu SOLDER BALLS

S Y M B O L	MILLIMETERS			N O T E
	MIN.	NOM.	MAX.	
A	2.70	~	3.50	
A₁	0.40	0.50	0.60	
A₂	0.90	~	1.50	
D/E	35.00 BASIC			
D1/E1	33.00 REF			
e	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa	~	~	0.20	
ccc	~	~	0.35	
ddd	~	~	0.25	
eee	~	~	0.10	
M	34			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994

2. SYMBOL 'M' IS THE BALL MATRIX SIZE

3. CONFORMS TO JEDEC MS–034–AAR–1

4. THIS PACKAGE IS ONLY USED FOR VIRTEX®–5 FPGAS REFER TO PK401 FOR THE MECHANICAL DRAWING OF THE FF1156 PACKAGE USED BY VIRTEX–6 FPGAS

pk384_01_121009

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/04/09	1.0	Initial Xilinx release.
12/14/09	1.1	Revised document title and added note 4 to indicate this package is a variation of the FF1156/FFG1156 type used only on Virtex-5 FPGAs.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.